

BUK6E3R4-40C

N-channel TrenchMOS intermediate level FET

Rev. 3 — 14 October 2010

Product data sheet

1. Product profile

1.1 General description

Intermediate level gate drive N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using advanced TrenchMOS technology. This product has been designed and qualified to the appropriate AEC Q101 standard for use in high performance automotive applications.

1.2 Features and benefits

- AEC Q101 compliant
- Suitable for intermediate level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V Automotive systems
- Electric and electro-hydraulic power steering
- Motors, lamps and solenoid control
- Start-Stop micro-hybrid applications
- Transmission control
- Ultra high performance power switching

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$	-	-	40	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; see Figure 1	11	-	100	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; see Figure 2	-	-	204	W
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 25\text{ A}$; $T_j = 25\text{ °C}$; see Figure 11	-	3.05	3.6	mΩ



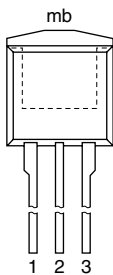
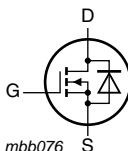
Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 100\text{ A}$; $V_{sup} \leq 40\text{ V}$; $R_{GS} = 50\ \Omega$; $V_{GS} = 10\text{ V}$; $T_{j(init)} = 25\text{ }^\circ\text{C}$; unclamped	-	-	368	mJ
Dynamic characteristics						
Q_{GD}	gate-drain charge	$I_D = 25\text{ A}$; $V_{DS} = 32\text{ V}$; $V_{GS} = 10\text{ V}$; see Figure 13 ; see Figure 14	-	42	-	nC

[1] Continuous current is limited by package.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	Drain		
3	S	source		
mb	D	mounting base; connected to drain		

SOT226 (I2PAK)

3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BUK6E3R4-40C	I2PAK	plastic single-ended package (I2PAK); TO-262	SOT226

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$	-	40	V
V_{GS}	gate-source voltage	Pulsed [1]	-20	20	V
		DC [2]	-16	16	V
I_D	drain current	$T_{mb} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$; see Figure 1 [3]	-	100	A
		$T_{mb} = 100\text{ °C}$; $V_{GS} = 10\text{ V}$; see Figure 1 [3]	-	100	A
I_{DM}	peak drain current	$T_{mb} = 25\text{ °C}$; $t_p \leq 10\text{ }\mu\text{s}$; pulsed; see Figure 3	-	657	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; see Figure 2	-	204	W
T_{stg}	storage temperature		-55	175	°C
T_j	junction temperature		-55	175	°C
Source-drain diode					
I_S	source current	$T_{mb} = 25\text{ °C}$ [3]	-	100	A
I_{SM}	peak source current	$t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ °C}$	-	657	A
Avalanche ruggedness					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 100\text{ A}$; $V_{sup} \leq 40\text{ V}$; $R_{GS} = 50\text{ }\Omega$; $V_{GS} = 10\text{ V}$; $T_{j(init)} = 25\text{ °C}$; unclamped	-	368	mJ
$E_{DS(AL)R}$	repetitive drain-source avalanche energy	[4] [5] [6]	-	-	J

[1] Accumulated pulse duration not to exceed 5mins.

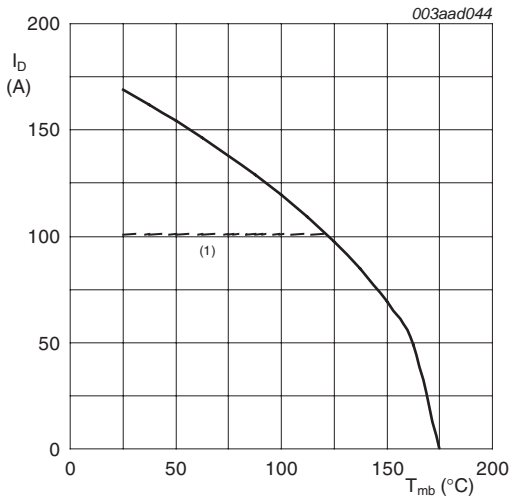
[2] -16V accumulated duration not to exceed 168 hrs.

[3] Continuous current is limited by package.

[4] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.

[5] Repetitive avalanche rating limited by an average junction temperature of 170 °C.

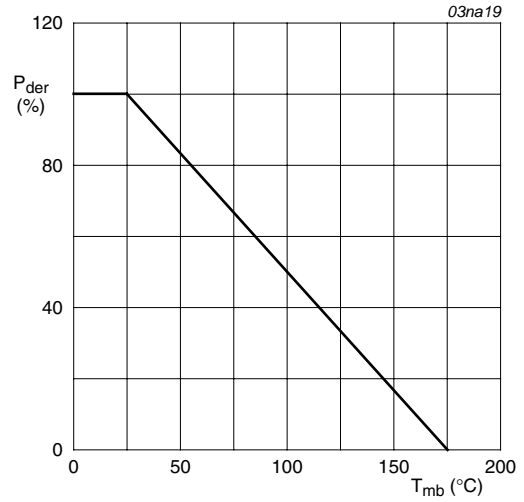
[6] Refer to application note AN10273 for further information.



$V_{GS} \geq 10$ V

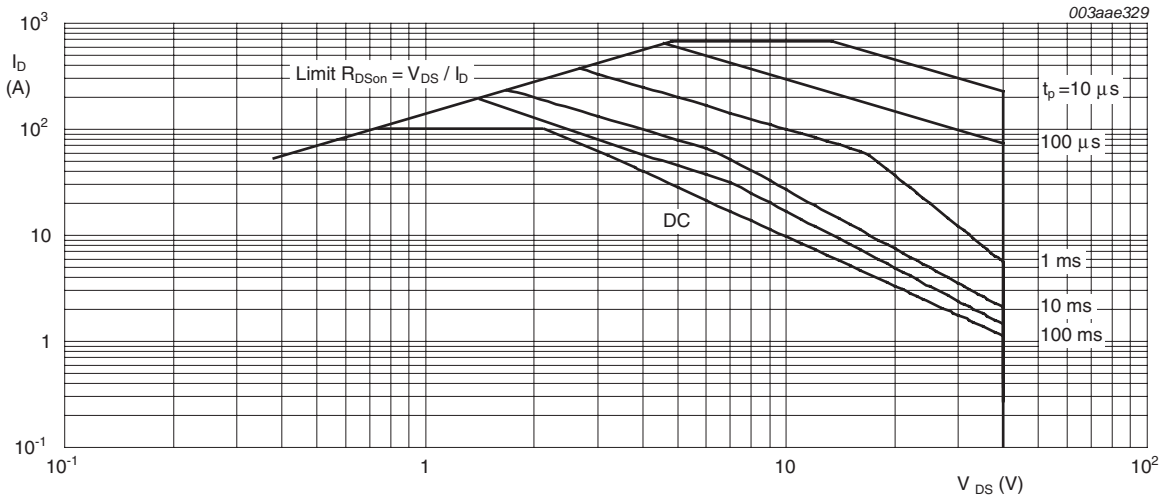
(1) Capped at 100 A due to package.

Fig 1. Continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$T_{mb} = 25$ °C; I_{DM} is a single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	0.74	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	vertical in free air	-	60	-	K/W

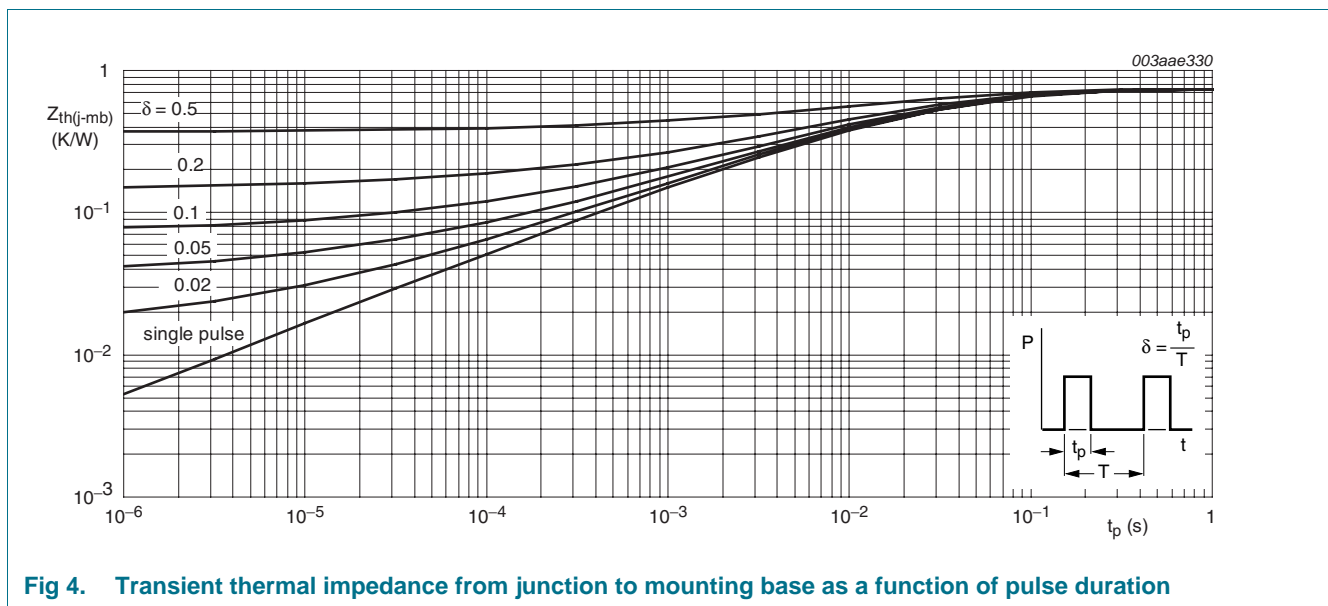


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

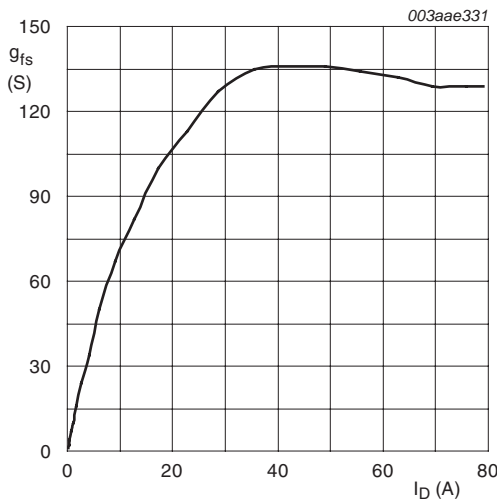
6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	40	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$	36	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ C$; see Figure 9 ; see Figure 10	1.8	2.3	2.8	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ C$; see Figure 10	-	-	3.3	V
		$I_D = 2.5 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ C$; see Figure 10	0.8	-	-	V
I_{DSS}	drain leakage current	$V_{DS} = 40 V; V_{GS} = 0 V; T_j = 175 \text{ }^\circ C$	-	-	500	μA
		$V_{DS} = 40 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	-	0.02	1	μA
I_{GSS}	gate leakage current	$V_{DS} = 0 V; V_{GS} = 20 V; T_j = 25 \text{ }^\circ C$	-	2	100	nA
		$V_{DS} = 0 V; V_{GS} = -20 V; T_j = 25 \text{ }^\circ C$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10 V; I_D = 25 A; T_j = 25 \text{ }^\circ C$; see Figure 11	-	3.05	3.6	m Ω
		$V_{GS} = 5 V; I_D = 25 A; T_j = 25 \text{ }^\circ C$; see Figure 11	-	4.2	5.3	m Ω
		$V_{GS} = 4.5 V; I_D = 25 A; T_j = 25 \text{ }^\circ C$; see Figure 11	-	4.5	6	m Ω
		$V_{GS} = 10 V; I_D = 25 A; T_j = 175 \text{ }^\circ C$; see Figure 12 ; see Figure 11	-	-	7.6	m Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 25 A; V_{DS} = 32 V; V_{GS} = 10 V$; see Figure 13 ; see Figure 14	-	125	-	nC
		$I_D = 25 A; V_{DS} = 32 V; V_{GS} = 5 V$; see Figure 13 ; see Figure 14	-	71	-	nC
Q_{GS}	gate-source charge	$I_D = 25 A; V_{DS} = 32 V; V_{GS} = 10 V$; see Figure 13 ; see Figure 14	-	23	-	nC
Q_{GD}	gate-drain charge	$I_D = 25 A; V_{DS} = 32 V; V_{GS} = 10 V$; see Figure 13 ; see Figure 14	-	42	-	nC
C_{iss}	input capacitance	$V_{GS} = 0 V; V_{DS} = 25 V; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$; see Figure 15	-	6016	8020	pF
C_{oss}	output capacitance	$V_{GS} = 0 V; V_{DS} = 25 V; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$; see Figure 15	-	739	870	pF
C_{rss}	reverse transfer capacitance	$V_{GS} = 0 V; V_{DS} = 25 V; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$; see Figure 15	-	510	700	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 30 V; R_L = 1.2 \text{ } \Omega; V_{GS} = 10 V; R_{G(ext)} = 10 \text{ } \Omega$	-	40	-	ns
t_r	rise time	$V_{DS} = 30 V; R_L = 1.2 \text{ } \Omega; V_{GS} = 10 V; R_{G(ext)} = 10 \text{ } \Omega$	-	87	-	ns
$t_{d(off)}$	turn-off delay time	$V_{DS} = 30 V; R_L = 1.2 \text{ } \Omega; V_{GS} = 10 V; R_{G(ext)} = 10 \text{ } \Omega$	-	224	-	ns
t_f	fall time	$V_{DS} = 30 V; R_L = 1.2 \text{ } \Omega; V_{GS} = 10 V; R_{G(ext)} = 10 \text{ } \Omega$	-	117	-	ns
L_D	internal drain inductance	from drain lead 6 mm from package to centre of die; $T_j = 25 \text{ }^\circ C$	-	4.5	-	nH
L_S	internal source inductance	from source lead to source bond pad; $T_j = 25 \text{ }^\circ C$	-	7.5	-	nH

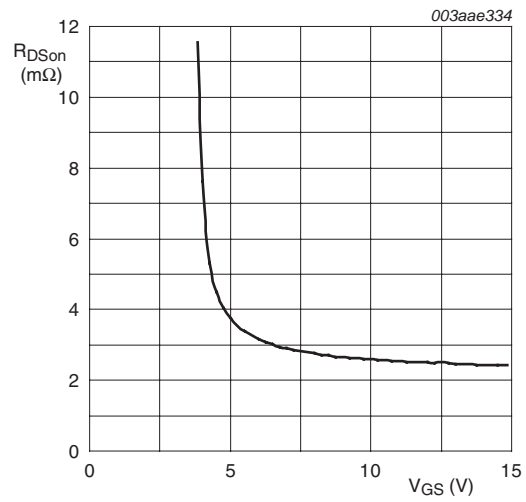
Table 6. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 25\text{ A}$; $V_{GS} = 0\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$; see Figure 16	-	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 20\text{ A}$; $di_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$;	-	48	-	ns
Q_r	recovered charge	$V_{DS} = 25\text{ V}$	-	82	-	nC



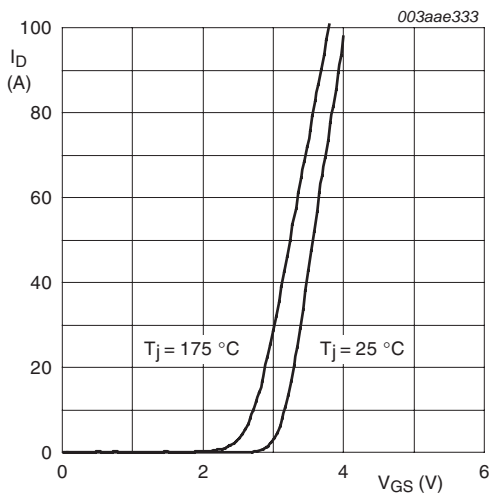
$T_j = 25\text{ }^\circ\text{C}$; $V_{DS} = 25\text{ V}$

Fig 5. Forward transconductance as a function of drain current; typical values



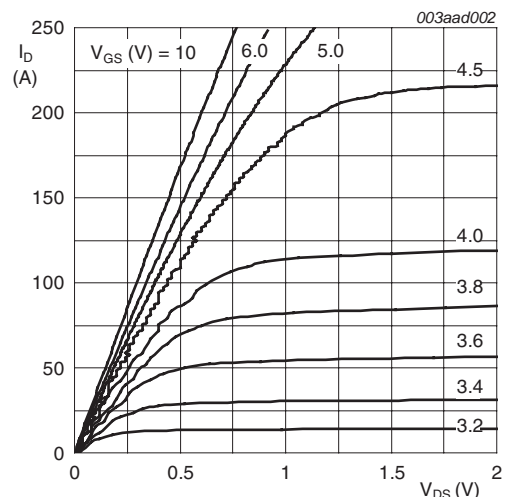
$T_j = 25\text{ }^\circ\text{C}$; $I_D = 25\text{ A}$

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values



$V_{DS} = 25\text{ V}$

Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$T_j = 25\text{ }^\circ\text{C}$

Fig 8. Output characteristics: drain current as a function of drain-source voltage; typical values

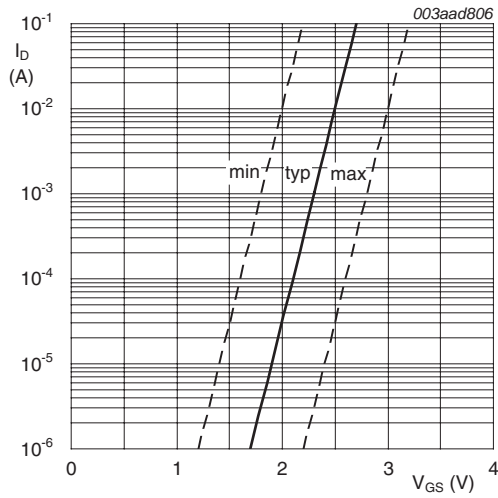


Fig 9. Sub-threshold drain current as a function of gate-source voltage

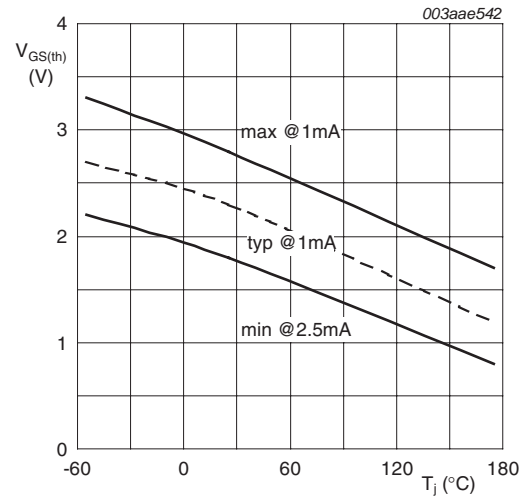


Fig 10. Gate-source threshold voltage as a function of junction temperature

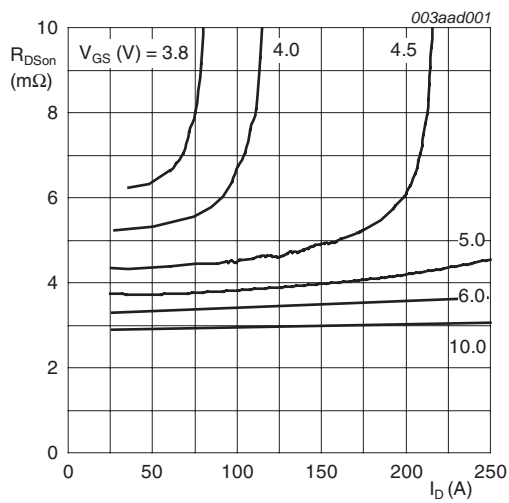


Fig 11. Drain-source on-state resistance as a function of drain current; typical values

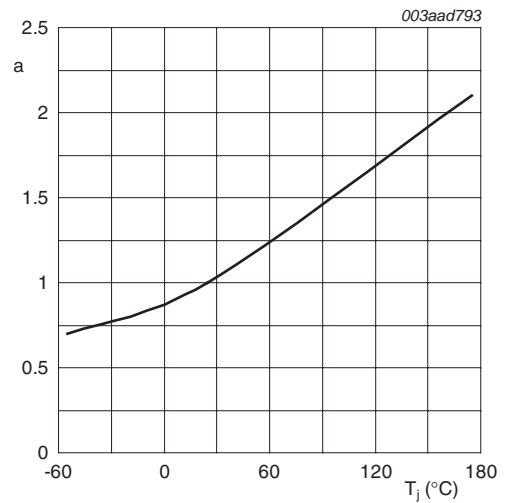


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature

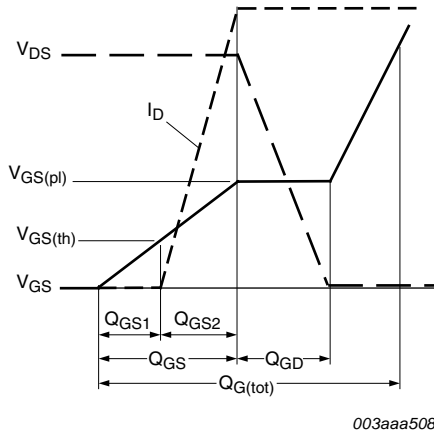
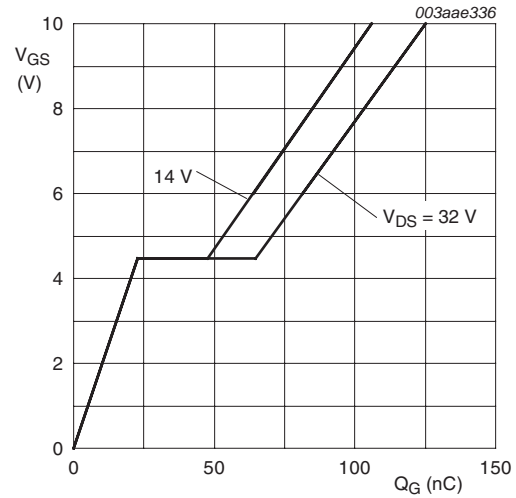
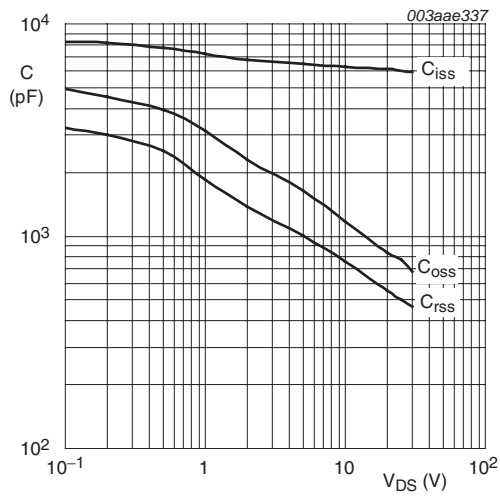


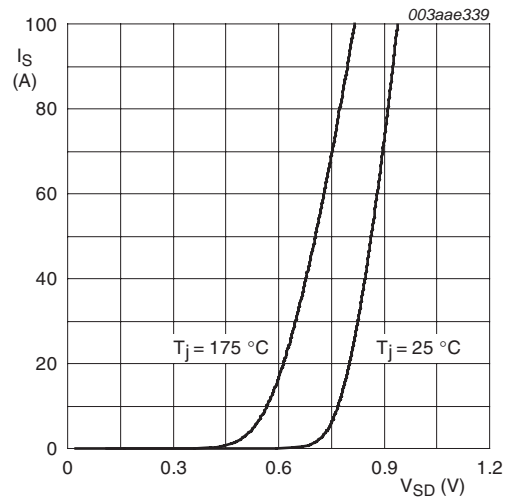
Fig 13. Gate charge waveform definitions



$T_j = 25\text{ }^\circ\text{C}; I_D = 25\text{ A}$
Fig 14. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{ V}; f = 1\text{ MHz}$
Fig 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0\text{ V}$
Fig 16. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

7. Package outline

Plastic single-ended package (I2PAK); low-profile 3-lead TO-262

SOT226

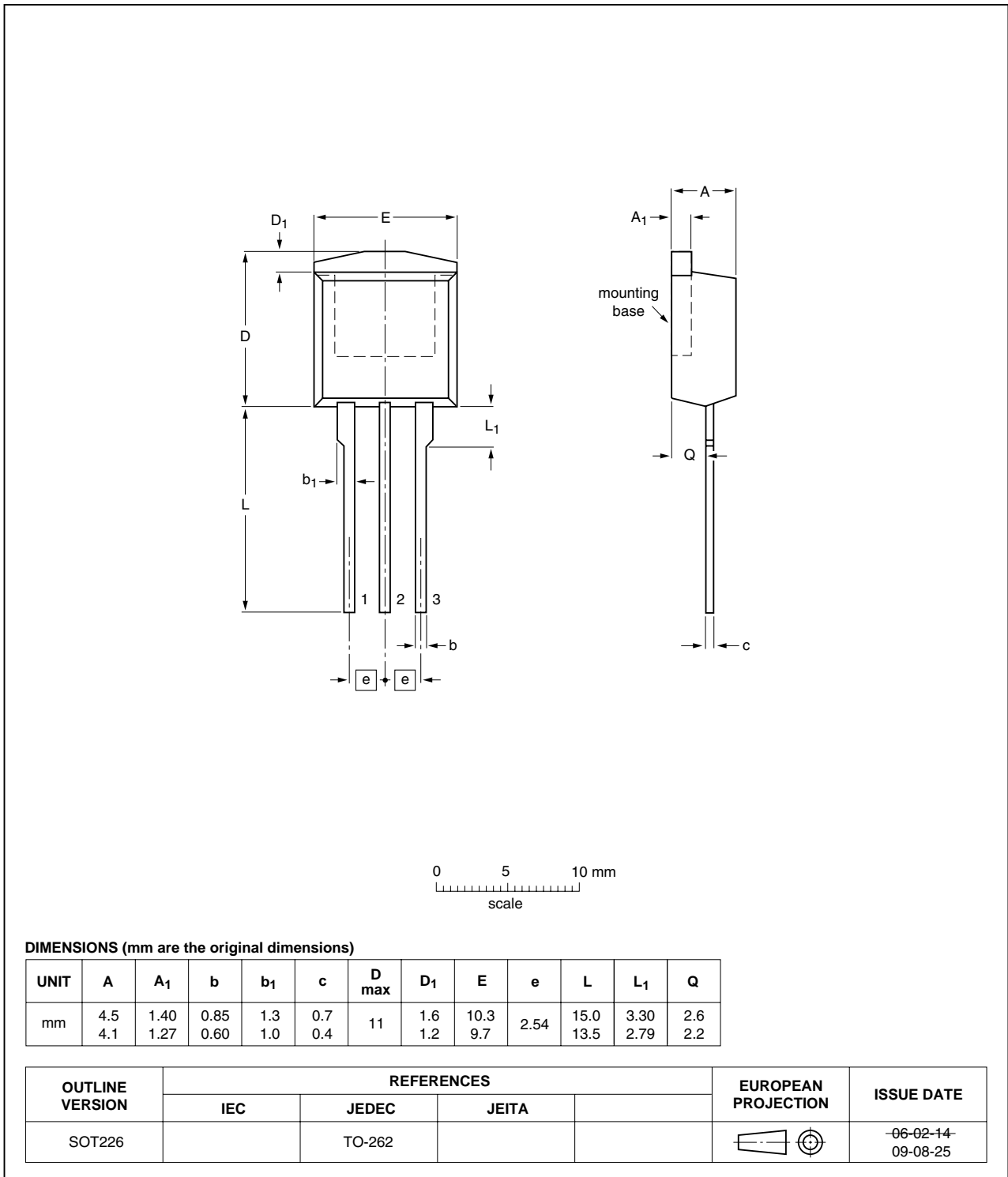


Fig 17. Package outline SOT226 (I2PAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK6E3R4-40C v.3	20101014	Product data sheet	-	BUK6E3R4-40C v.2
Modifications:	• Status changed from objective to product.			
BUK6E3R4-40C v.2	20100621	Objective data sheet	-	BUK6E3R4-40C v.1

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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